



Material Content Data Sheet



Sales Product Name				IPB60R040CFD7		Issued		4. July 2019	
MA#				MA002768238					
Package				PG-TO263-3-2		Weight*		1566.31 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	15.501	0.99	0.99	9897	9897	
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58		
	non noble metal	iron	7439-89-6	0.304	0.02		194		
	non noble metal	copper	7440-50-8	304.026	19.41	19.44	194104	194356	
	non noble metal	aluminium	7429-90-5	8.189	0.52	0.52	5228	5228	
wire	non noble metal	aluminium	7429-90-5	8.189	0.52	0.52	5228	5228	
encapsulation	organic material	carbon black	1333-86-4	10.060	0.64		6423		
	plastics	epoxy resin	-	110.658	7.06		70649		
	inorganic material	silicondioxide	60676-86-0	549.937	35.11	42.81	351104	428176	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6165	6165	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147	
solder	non noble metal	tin	7440-31-5	0.186	0.01		118		
	noble metal	silver	7440-22-4	0.232	0.01		148		
	non noble metal	lead	7439-92-1	8.859	0.57	0.59	5656	5922	
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105		
	non noble metal	iron	7439-89-6	0.548	0.04		350		
	non noble metal	copper	7440-50-8	547.666	34.97	35.02	349654	350109	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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